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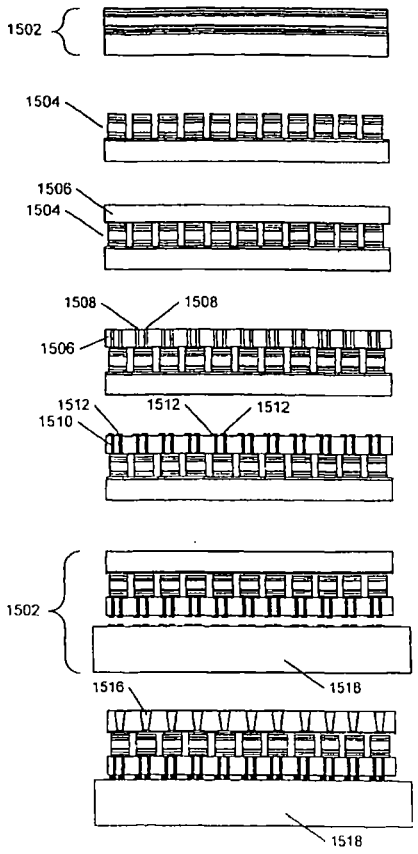
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(54) Title: OPTO-ELECTRONIC DEVICE INTEGRATION



(57) Abstract: A method for creating a hybridized chip having at least one bottom active device (1504) coupled to an electronic chip (1518) includes combining a bottom active optical device and an electronic chip when at least some of the bottom active optical device contacts are not aligned with at least some of the electronic chip contacts. The method involves adding an insulating layer (1506), having a thickness, a first side and a second side, to the bottom active optical device by affixing the first side of the insulating layer to the surface of the bottom active optical device opposite the substrate, forming openings in the insulating layer extending from the second side to the first side at points substantially coincident with the active contacts of the optical device and the electronic chip, making the sidewalls electrically conductive, and connecting the points with the bottom active optical device contacts and the electronic chip contacts with an electrically conductive material.

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